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PRODUCT No POSITION LOADED CONTACT PLATING HSG COLOR NOTES 93899-001 93899-001LF NOTE 3 30u" GXT BLACK 10.16 -ø3.25±0.07 TYP(2) NOTES: 1. SPECIAL PACKAGING. -ø0.76±0.07 TYP(6) 2. GXT IS 0.76um /30u" MIN GXT WITH Au FLASH OVER 1.27um /50u" MIN Ni. 3. PACKAGING SPEC. BUS-14-164. 4. THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER 1.91 COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. 5. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK BOARD LAYOUT TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION VIEWED FROM TOP WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD. 6. IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.

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PDM: Rev:F

STATUS: Released

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